

## CMOS-CCD 1H Delay Line for NTSC with PLL

### Description

The CXL5005M/P are general-purpose CCD delay line ICs which provide 1H delay time of NTSC.

### Features

- Low power consumption 90mW (Typ.)
- Small size package (14-pin SOP, DIP)
- Low differential gain DG = 3% (Typ.)
- Input signal amplitude 180 IRE (= 1.28Vp-p, max.)
- Low input clock amplitude operation 200mVp-p (Min.)
- Built-in triple PLL circuit
- Built-in peripheral circuits (clock driver, timing generator, auto-bias and output circuits)

### Functions

- 680-bit CCD register
- Clock drivers
- Autobias circuit
- Sync tip clamp circuit
- Sample-and-hold circuit
- PLL (triple)

### Structure

CMOS-CCD

### Absolute Maximum Ratings (Ta = 25°C)

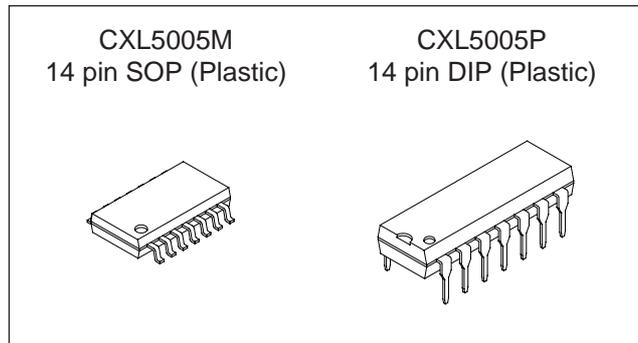
• Supply voltage	V <sub>DD</sub>	11	V
• Supply voltage	V <sub>CL</sub>	6	V
• Operating temperature	T <sub>opr</sub>	-10 to +60	°C
• Storage temperature	T <sub>stg</sub>	-55 to +150	°C
• Allowable power dissipation	P <sub>D</sub>		
		CXL5005M	400 mW
		CXL5005P	800 mW

### Recommended Operating Conditions

Supply voltage	V <sub>DD</sub>	9 ± 5%	V
	V <sub>CL</sub>	5 ± 5%	V

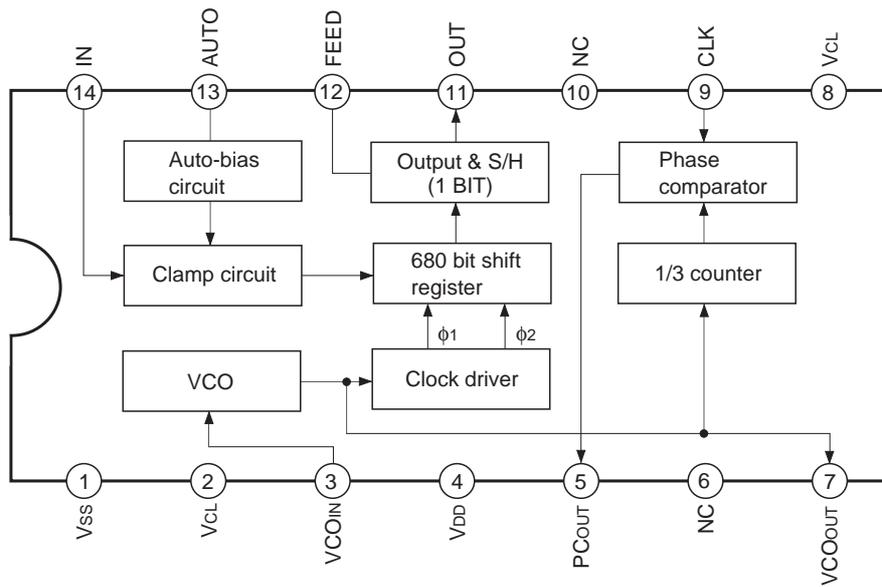
### Recommended Clock Conditions

- Input clock amplitude V<sub>CLK</sub> 200mVp-p to 1.0Vp-p (300mVp-p typ.)
- Clock frequency f<sub>CLK</sub> 3.579545MHz



Sony reserves the right to change products and specifications without prior notice. This information does not convey any license by any implication or otherwise under any patents or other right. Application circuits shown, if any, are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits.

**Block Diagram and Pin configuration**



**Pin Description**

Pin No.	Symbol	Description	Impedance [ $\Omega$ ]
1	V <sub>SS</sub>	GND	
2	V <sub>CL</sub>	5V power supply	
3	V <sub>COIN</sub>	VCO input	> 100k
4	V <sub>DD</sub>	9V power supply	
5	PC <sub>OUT</sub>	Phase comparator output	≈ 5k
6	NC		
7	V <sub>COOUT</sub>	VCO output	≈ 5k
8	V <sub>CL</sub>	5V power supply	
9	CLK	Clock input	≈ 5k
10	NC		
11	OUT	Signal output	600 to 1k
12	FEED	Feedback DC output	> 100k
13	AUTO	Autobias DC output	≈ 10k
14	IN	Signal input	> 100k

## Electrical Characteristics

( $T_a = 25^\circ\text{C}$ ,  $V_{DD} = 9.0\text{V}$ ,  $V_{CL} = 5.0\text{V}$ ,  $f_{CLK} = 3.58\text{MHz}$ ,  $V_{CLK} = 300\text{mVp-p}$  sine wave,  
See "Electrical Characteristics Test Circuit")

Item	Symbol	Test condition	SW condition		Measuring point	Min.	Typ.	Max.	Unit
			1	2					
Supply current	I <sub>DD</sub>	250kHz, 1.28Vp-p, sine wave input	a	a	A1	—	4.0	5.0	mA
	I <sub>CL</sub>				A2	—	9.0	12.0	mA
Insertion gain	IG	250kHz, 1.28Vp-p, sine wave input IG = 20 log (Output voltage [Vp-p] / 1.28 [Vp-p])	a	a	V1	-3.0	0.0	3.0	dB
Frequency response	fG	Dissipation at 3.58MHz in relation to 250kHz fG = 20 log (V <sub>3.58MHz</sub> / V <sub>250kHz</sub> ) <b>(Note 1)</b>	b, c	b	V1	-3.0	-2.1	—	dB
Differential gain	DG	5-staircase wave input Y = 140 IRE (= 1.0Vp-p) Measure with vector scope <b>(Note 2)</b>	e	a	S	—	3.0	5.0	%
Differential phase	DP					—	3.0	5.0	deg
Allowable input amplitude	V <sub>IN-AC</sub>		—	—	—	—	—	1.28	Vp-p
Noise	S/N	S: Input = 250kHz, 1.0Vp-p output (Vp-p)	f	a	V2	55	60	—	dB
		N: Input = DC GND output (V <sub>rms</sub> )	d	a					
DC output voltage	V <sub>IN-DC</sub>		d	a	V3	3.5	5.0	6.5	V
	V <sub>AUTO-DC</sub>				V4	3.5	5.0	6.5	V
	V <sub>FEED-DC</sub>	250kHz, 1.28Vp-p, sine wave input	a	a	V5	1.3	2.3	3.3	V
	V <sub>OUT-DC</sub>				V6	1.7	2.7	3.7	V

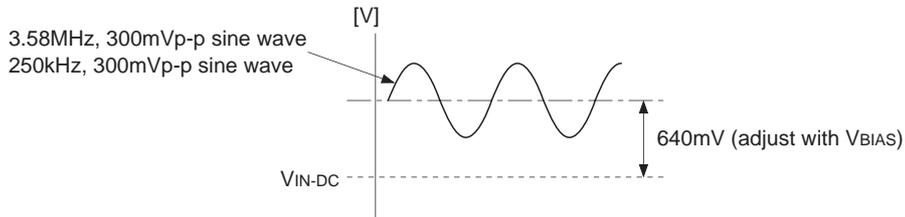


**Note 1) Frequency response test condition**

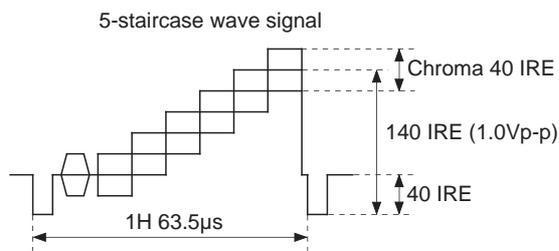
$V_{3.58\text{MHz}}$  (Output signal voltage [Vp-p] at 3.58MHz input)

$V_{250\text{kHz}}$  (Output signal voltage [Vp-p] at 250kHz input)

Set Pin 14 (IN) voltage [V] =  $V_{\text{IN-DC}} + 640\text{mV}$ .

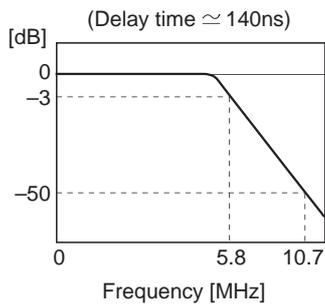


**Note 2) Differential gain and differential phase test condition**

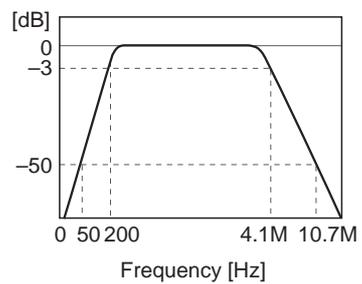


DG and DP are measured at output S point by vector scope.

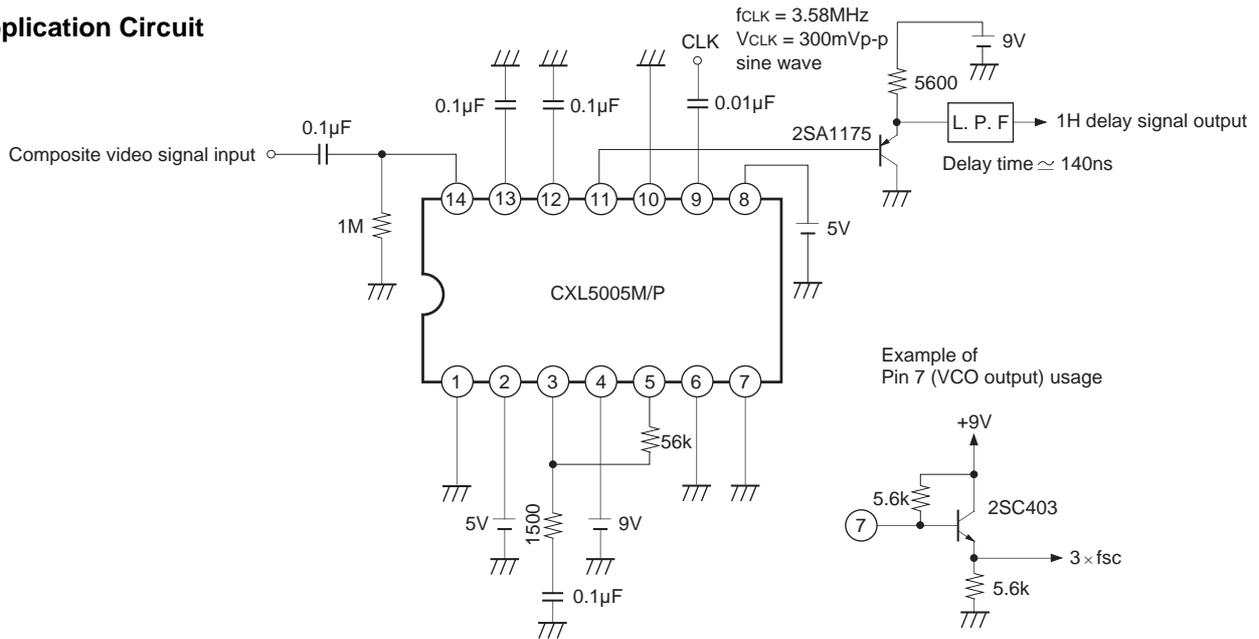
**Note 3) LPF frequency response**



**Note 4) BPF frequency response**

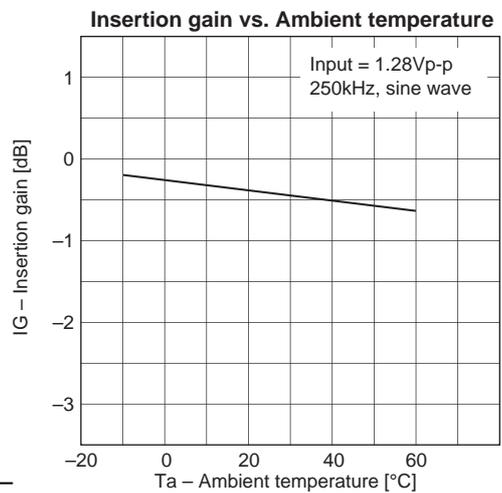
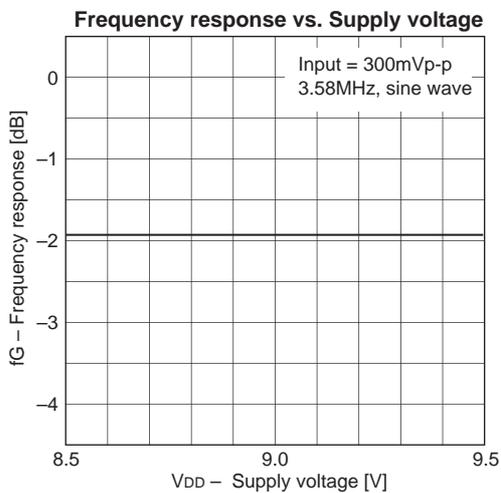
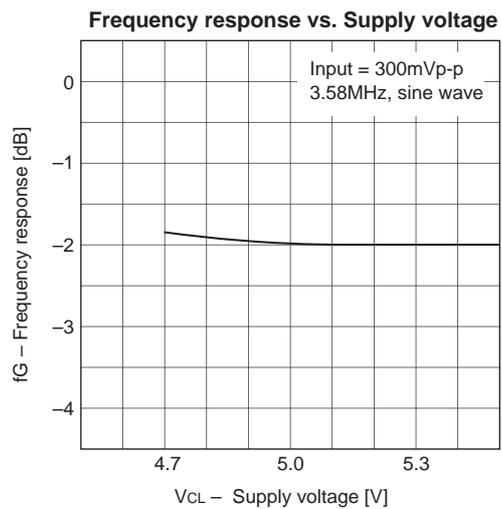
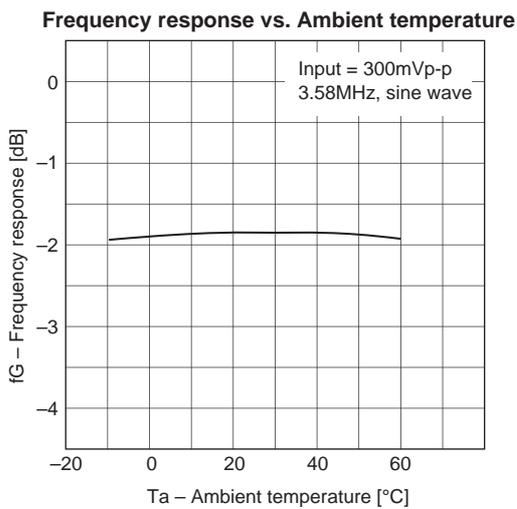


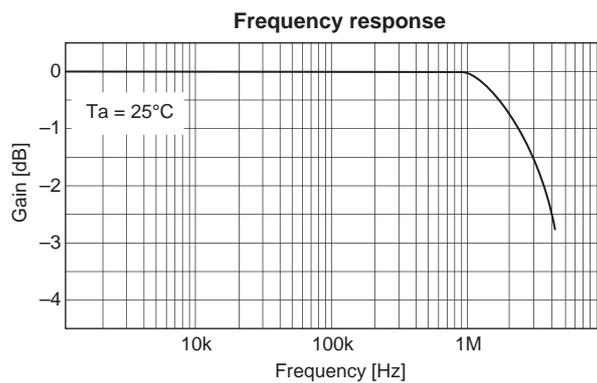
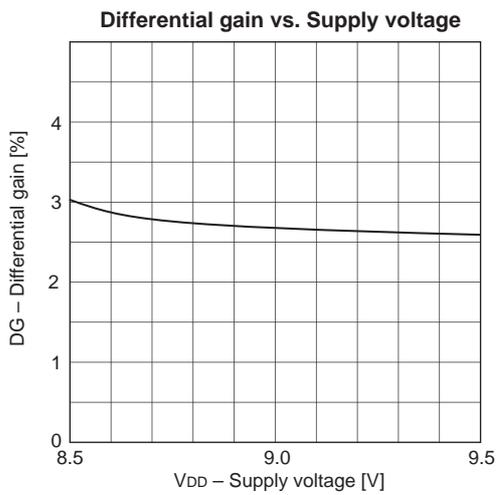
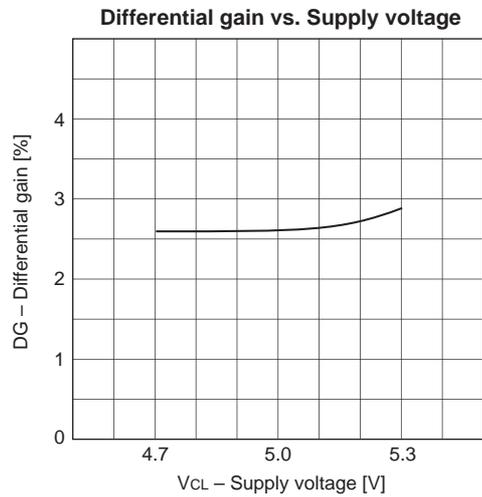
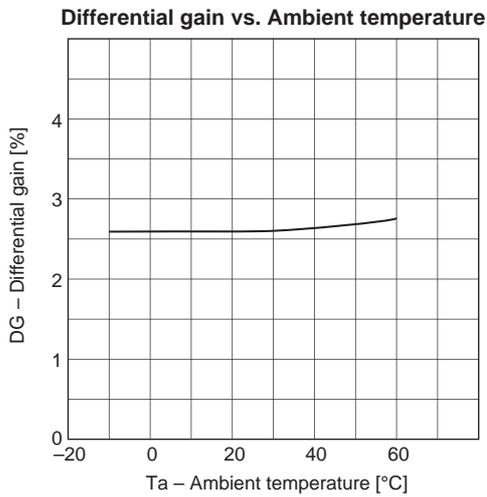
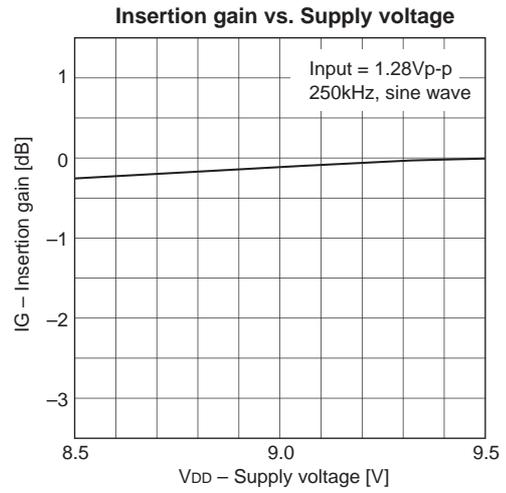
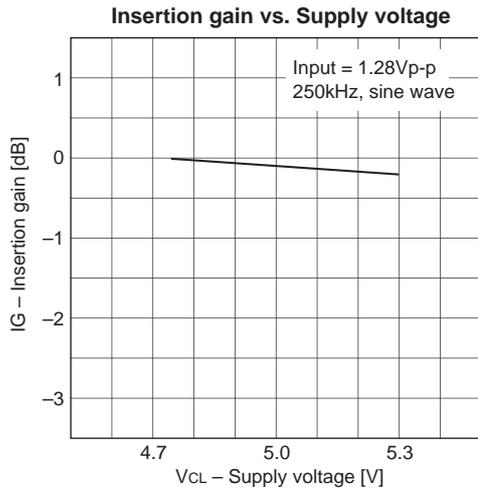
Application Circuit



Application circuits shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party patent and other right due to same.

Example of Representative Characteristics

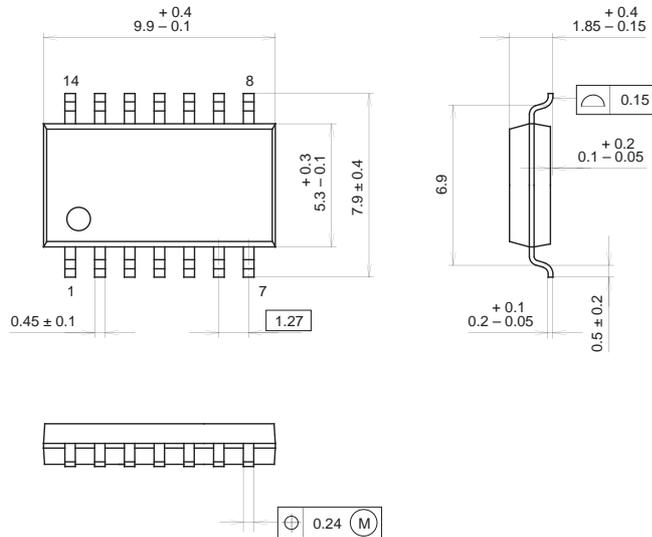




Package Outline Unit: mm

CXL5005M

14PIN SOP (PLASTIC)



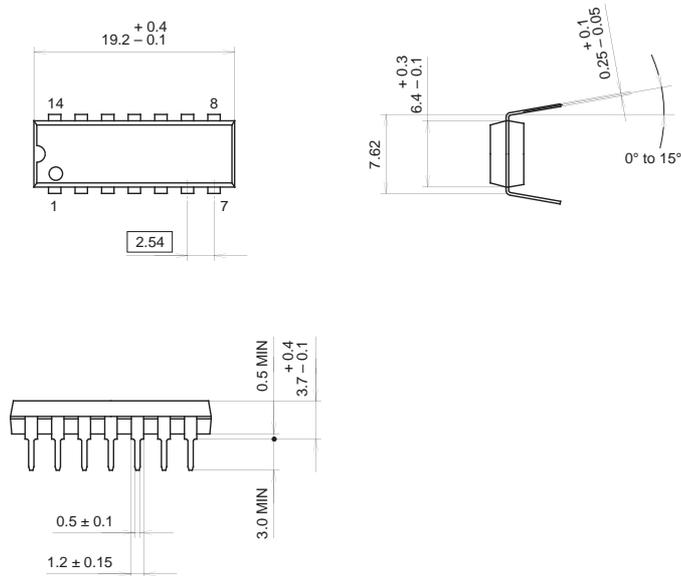
PACKAGE STRUCTURE

SONY CODE	SOP-14P-L01
EIAJ CODE	SOP014-P-0300
JEDEC CODE	

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42/COPPER ALLOY
PACKAGE MASS	0.2g

CXL5005P

14PIN DIP (PLASTIC)



PACKAGE STRUCTURE

SONY CODE	DIP-14P-01
EIAJ CODE	DIP014-P-0300
JEDEC CODE	Similar to MO-001-AH

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42/COPPER ALLOY
PACKAGE MASS	0.9g